

SN54ALS688, SN74ALS688 8-BIT IDENTITY COMPARATORS

SDAS228A – JUNE 1982 – REVISED JANUARY 1995

- Compare Two 8-Bit Words
- Totem-Pole Outputs ($\overline{P = Q}$)
- 'ALS688 Are Identical to 'ALS521
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

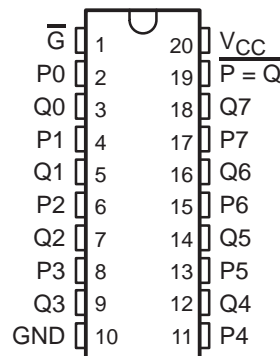
These identity comparators perform comparisons on two 8-bit binary or BCD words and provide $\overline{P = Q}$ outputs. These devices have totem-pole outputs.

The SN54ALS688 is characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS688 is characterized for operation from 0°C to 70°C .

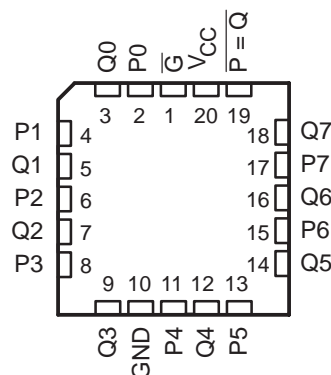
FUNCTION TABLE

| INPUTS | | OUTPUT $\overline{P = Q}$ |
|--------------|--------------------------|------------------------------|
| DATA P, Q | ENABLE \overline{G} | |
| $P = Q$ | L | L |
| $P > Q$ | L | H |
| $P < Q$ | L | H |
| X | H | H |

SN54ALS688 . . . J PACKAGE
SN74ALS688 . . . DW OR N PACKAGE
(TOP VIEW)



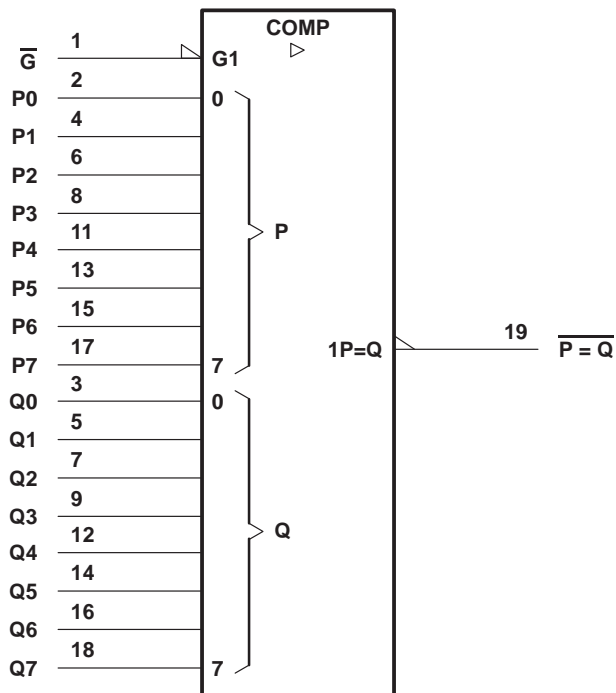
SN54ALS688 . . . FK PACKAGE
(TOP VIEW)



SN54ALS688, SN74ALS688 8-BIT IDENTITY COMPARATORS

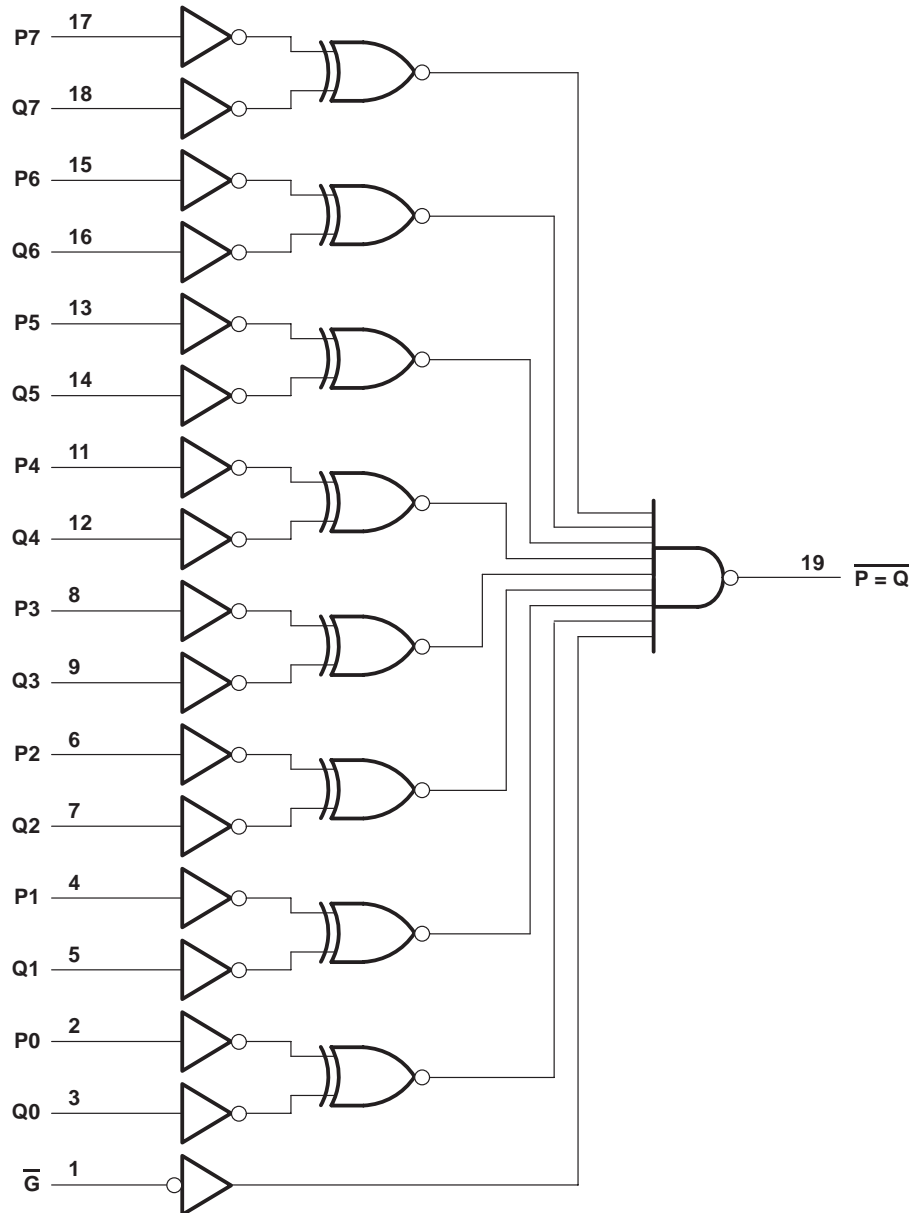
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

| | |
|--|----------------|
| Supply voltage, V_{CC} | 7 V |
| Input voltage, V_I | 7 V |
| Operating free-air temperature range, T_A : SN54ALS688 | –55°C to 125°C |
| SN74ALS688 | 0°C to 70°C |
| Storage temperature range | –65°C to 150°C |

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SN54ALS688, SN74ALS688 8-BIT IDENTITY COMPARATORS

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recommended operating conditions

| | | SN54ALS688 | | | SN74ALS688 | | | UNIT |
|----------|--------------------------------|------------|-----|-----|------------|-----|------|------|
| | | MIN | NOM | MAX | MIN | NOM | MAX | |
| V_{CC} | Supply voltage | 4.5 | 5 | 5.5 | 4.5 | 5 | 5.5 | V |
| V_{IH} | High-level input voltage | 2 | | | 2 | | | V |
| V_{IL} | Low-level input voltage | | | 0.7 | | | 0.8 | V |
| I_{OH} | High-level output current | | | -1 | | | -2.6 | mA |
| I_{OL} | Low-level output current | | | 12 | | | 24 | mA |
| T_A | Operating free-air temperature | -55 | | 125 | 0 | | 70 | °C |

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | SN54ALS688 | | | SN74ALS688 | | | UNIT |
|--------------------|---|--|--------------|------|------|--------------|------|------|------|
| | | | MIN | TYP† | MAX | MIN | TYP† | MAX | |
| V_{IK} | $V_{CC} = 4.5\text{ V}$, $I_I = -18\text{ mA}$ | | | | -1.5 | | | -1.5 | V |
| V_{OH} | $V_{CC} = 4.5\text{ V to } 5.5\text{ V}$, $I_{OH} = -0.4\text{ mA}$ | | $V_{CC} - 2$ | | | $V_{CC} - 2$ | | | V |
| | $V_{CC} = 4.5\text{ V}$, $I_{OH} = -1\text{ mA}$ | | 2.4 | 3.3 | | | | | |
| | $V_{CC} = 4.5\text{ V}$, $I_{OH} = -2.6\text{ mA}$ | | | | | 2.4 | 3.3 | | |
| V_{OL} | $V_{CC} = 4.5\text{ V}$, $I_{OL} = 12\text{ mA}$ | | | 0.25 | 0.4 | | 0.25 | 0.4 | V |
| | $V_{CC} = 4.5\text{ V}$, $I_{OL} = 24\text{ mA}$ | | | | | | 0.35 | 0.5 | |
| I_I | $V_{CC} = 5.5\text{ V}$, $V_I = 7\text{ V}$ | | | | 0.1 | | | 0.1 | mA |
| I_{IH} | $V_{CC} = 5.5\text{ V}$, $V_I = 2.7\text{ V}$ | | | | 20 | | | 20 | μA |
| I_{IL} | $V_{CC} = 5.5\text{ V}$, $V_I = 0.4\text{ V}$ | | | | -0.1 | | | -0.1 | mA |
| I_{O}^{\ddagger} | $V_{CC} = 5.5\text{ V}$, $V_O = 2.25\text{ V}$ | | -20 | | -112 | -30 | | -112 | mA |
| I_{CC} | $V_{CC} = 5.5\text{ V}$, See Note 1 | | | 12 | 19 | | 12 | 19 | mA |

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

NOTE 1: I_{CC} is measured with \bar{G} grounded, P and Q at 4.5 V.

switching characteristics (see Figure 1)

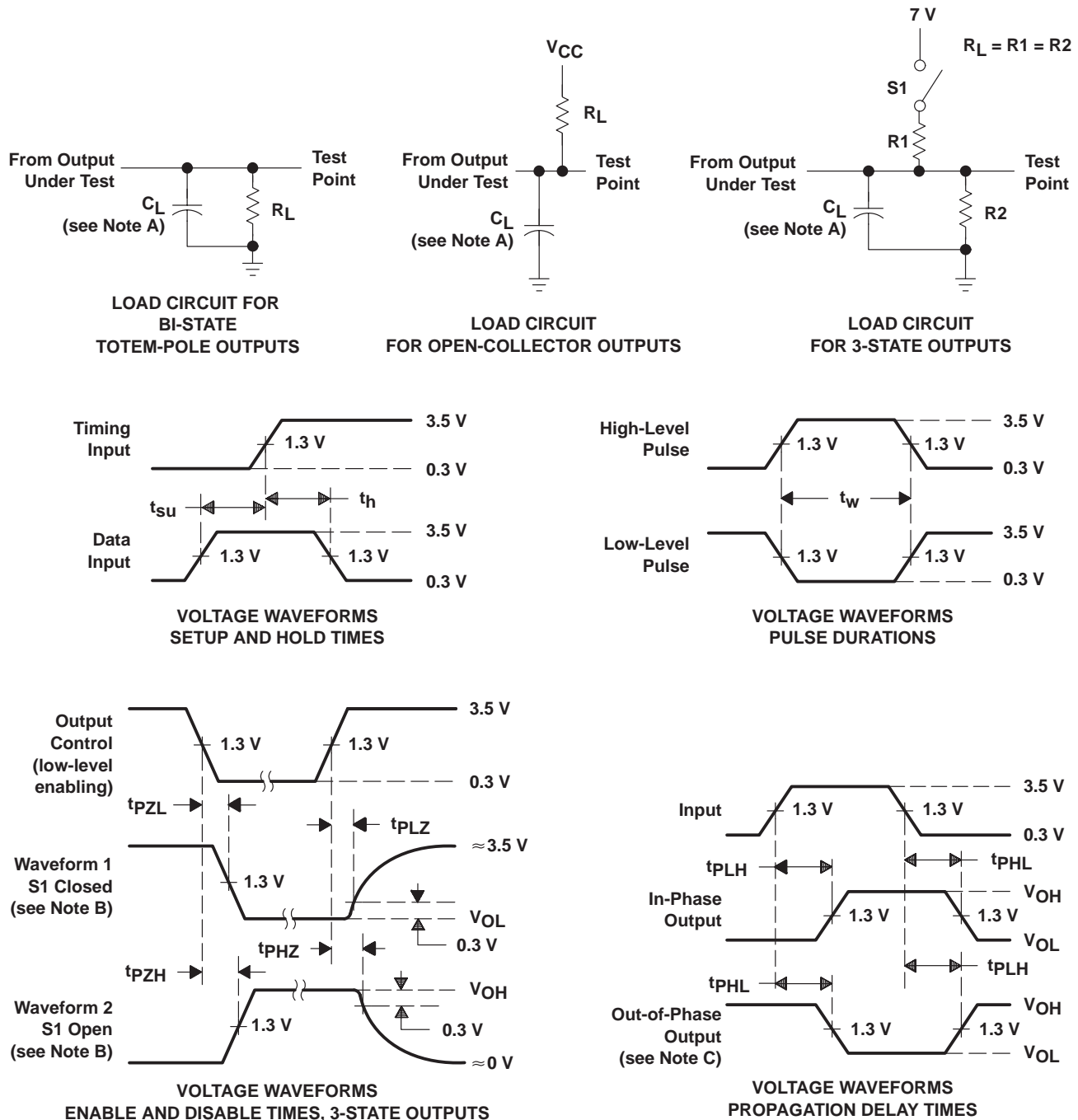
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX§ | | | | UNIT |
|------------------|-----------------|--------------------|---|-----|------------|-----|------|
| | | | SN54ALS688 | | SN74ALS688 | | |
| | | | MIN | MAX | MIN | MAX | |
| t _{PLH} | P | $\overline{P = Q}$ | 3 | 16 | 3 | 12 | ns |
| t _{PHL} | | | 5 | 25 | 5 | 20 | |
| t _{PLH} | Q | $\overline{P = Q}$ | 3 | 16 | 3 | 12 | ns |
| t _{PHL} | | | 5 | 25 | 5 | 20 | |
| t _{PLH} | \overline{G} | $\overline{P = Q}$ | 3 | 15 | 3 | 12 | ns |
| t _{PHL} | | | 5 | 25 | 5 | 22 | |

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
D. All input pulses have the following characteristics: $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|---------------------|--------------------------------------|----------------------|--------------|---|-------------------------|
| 5962-88578012A | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962- 88578012A SNJ54ALS 688FK | Samples |
| 5962-8857801RA | ACTIVE | CDIP | J | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8857801RA SNJ54ALS688J | Samples |
| 5962-8857801SA | ACTIVE | CFP | W | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8857801SA SNJ54ALS688W | Samples |
| SN54ALS688J | ACTIVE | CDIP | J | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | SN54ALS688J | Samples |
| SN74ALS688DW | ACTIVE | SOIC | DW | 20 | 25 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | ALS688 | Samples |
| SN74ALS688DWG4 | ACTIVE | SOIC | DW | 20 | 25 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | ALS688 | Samples |
| SN74ALS688DWR | ACTIVE | SOIC | DW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | ALS688 | Samples |
| SN74ALS688N | ACTIVE | PDIP | N | 20 | 20 | RoHS & Non-Green | NIPDAU | N / A for Pkg Type | 0 to 70 | SN74ALS688N | Samples |
| SN74ALS688NSR | ACTIVE | SO | NS | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | 0 to 70 | ALS688 | Samples |
| SNJ54ALS688FK | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962- 88578012A SNJ54ALS 688FK | Samples |
| SNJ54ALS688J | ACTIVE | CDIP | J | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8857801RA SNJ54ALS688J | Samples |
| SNJ54ALS688W | ACTIVE | CFP | W | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-8857801SA SNJ54ALS688W | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of ≤ 1000 ppm threshold. Antimony trioxide based flame retardants must also meet the ≤ 1000 ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS688, SN74ALS688 :

● Catalog: [SN74ALS688](#)

● Military: [SN54ALS688](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74ALS688DWR | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |
| SN74ALS688NSR | SO | NS | 20 | 2000 | 330.0 | 24.4 | 8.4 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74ALS688DWR | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74ALS688NSR | SO | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| PINS ** DIM | 14 | 16 | 18 | 20 |
|----------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



| PINS ** | 14 | 16 | 18 | 20 |
|---------------------|------------------|------------------|------------------|------------------|
| DIM | | | | |
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS-001 VARIATION | AA | BB | AC | AD |



14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW0020A

PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220724/A 05/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

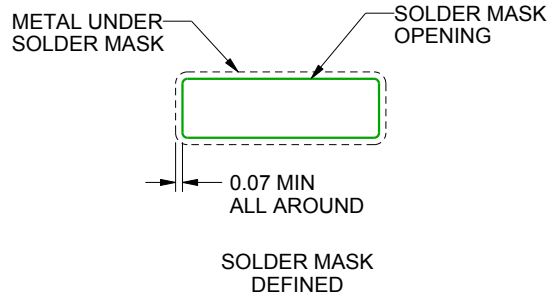
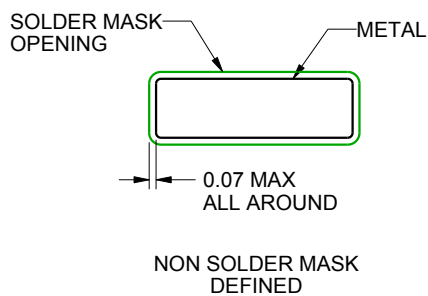
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



| NO. OF TERMINALS ** | A | | B | |
|---------------------------|------------------|------------------|------------------|------------------|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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